WHAT IS CLAIMED IS:

1. A method of producing an electronic device comprising the steps of :

forming a first substrate with at least a surface region, wherein the surface region is not planar;

attaching electrical contacts upon the surface region; and

attaching an electronic element comprising a flexible semiconductor to the electrical contacts, wherein the flexible semiconductor is bent to conform to the non-planar surface.

2. The method of claim 1 further comprising the step of placing the electronic device within an ophthalmic device.

3. The method of claim 2, wherein the surface region comprises a curved surface forming a support for at least a portion of a cylindrical shape electronic element.

4. The method of claim 3, wherein the cylindrical shape electronic element is oriented with its radial axis along an axis of the optical path of the ophthalmic device.

5. The method of claim 4, wherein the design of the electronic device is performed to include at least one redundant element.

6. The method of claim 4, wherein the semiconductor comprises crystalline silicon.

7. The method of claim 4, wherein the semiconductor comprises polycrystalline silicon.

8. The method of claim 4, wherein the semiconductor comprises amorphous silicon.

9. The method of claim 2, wherein the surface region comprises a curved surface wherein it forms a support for at least a portion of a cone shape electronic element.

10. The method of claim 9, wherein the cone shape is generally oriented with its radial axis along an axis of the optical path of the Ophthalmic Device.

11. The method of claim 10, wherein the design of the electronic device is performed to include at least one redundant element.

12. The method of claim 2, wherein the surface region comprises a curved surface wherein it forms a support comprising at least a portion of a non-flat flap shape.

13. The method of claim 12, wherein the flap shape is oriented with a surface whose surface normal is in the direction of the optical path of the ophthalmic device.

14. The method of claim 13, wherein the design of the electronic device is performed to include at least one redundant element.

15. An ophthalmic device comprising:

a substrate with at least a surface region, wherein at least a portion of the surface region is not planar across its extents;

electrical contacts formed upon the surface region; and

at least a first electronic element comprising a flexible semiconductor device attached to the electrical contacts, wherein the flexible semiconductor conforms to the non planar surface.

16. The ophthalmic device of claim 15, wherein the first surface region comprises a curved surface wherein it forms at least a portion of a cylindrical shape.

17. The ophthalmic device of claim 15, wherein the first surface region comprises a curved surface wherein it forms at least a portion of a cone shape.

18. The ophthalmic device of claim 15, wherein the first surface region comprises a curved surface wherein it forms at least a portion of a non-flat flap shape.

19. An ophthalmic device comprising:

a polymerized ophthalmic device encapsulating and shaping hydrogel layer;

a substrate with at least a surface region, wherein a portion of the surface region is planar across its extents and forms a flat flap shape;

electrical contacts formed upon the first surface region; and

an electronic element comprising a flexible semiconductor device attached to the electrical contacts, wherein the flexible semiconductor conforms to the non planar surface.

20. An ophthalmic device of claim 19, further comprising an electroactive optic component.

21. A method of producing an electronic device comprising the steps of:

forming a first substrate with at least one surface region, wherein the surface region is planar across its extents and forms a flat flap shape;

attaching electrical contacts upon the surface region; and

attaching an electronic element comprising a thin flexible semiconductor to the electrical contacts.

22. The method of claim 21, wherein the thin flexible semiconductor comprises a semiconductor layer upon an insulator layer.

23. The device of claim 22, wherein the flexible semiconductor comprises a semiconductor layer upon an insulator layer.

CLAIMS:

1. A method of producing an electronic device comprising the steps of:

forming a first substrate with at least a surface region, wherein the surface region is not planar;

attaching electrical contacts upon the surface region; and

attaching an electronic element comprising a flexible semiconductor to the electrical contacts, wherein the flexible semiconductor is bent to conform to a non-planar surface.

2. The method of claim 1 further comprising the step of placing the electronic device within an ophthalmic device.

3. The method of claim 2, wherein the surface region comprises a curved surface forming a support for at least a portion of a cylindrical shape electronic element.

4. The method of claim 3, wherein the cylindrical shape electronic element is oriented with its radial axis along an axis of the optical path of the ophthalmic device.

5. The method of claim 4, wherein the design of the electronic device is performed to include at least one redundant element.

6. The method of claim 4, wherein the semiconductor comprises crystalline silicon.

7. The method of claim 4, wherein the semiconductor comprises polycrystalline silicon.

8. The method of claim 4, wherein the semiconductor comprises amorphous silicon.

9. The method of claim 2, wherein the surface region comprises a curved surface wherein it forms a support for at least a portion of a cone shape electronic element.

10. The method of claim 9, wherein the cone shape is generally oriented with its radial axis along an axis of the optical path of the Ophthalmic Device.

11. The method of claim 10, wherein the design of the electronic device is performed to include at least one redundant element.

12. The method of claim 2, wherein the surface region comprises a curved surface wherein it forms a support comprising at least a portion of a non-flat flap shape.

13. The method of claim 12, wherein the flap shape is oriented with a surface whose surface normal is in the direction of the optical path of the ophthalmic device.

14. The method of claim 13, wherein the design of the electronic device is performed to include at least one redundant element.

15. An ophthalmic device comprising:

a substrate with at least a surface region, wherein at least a portion of the surface region is not planar across its extents;

electrical contacts formed upon the surface region; and

at least a first electronic element comprising a flexible semiconductor device attached to the electrical contacts, wherein the flexible semiconductor conforms to a non-planar surface.

16. The ophthalmic device of claim 15, wherein the surface region comprises a curved surface wherein it forms at least a portion of a cylindrical shape.

17. The ophthalmic device of claim 15, wherein the surface region comprises a

curved surface wherein it forms at least a portion of a cone shape.

18. The ophthalmic device of claim 15, wherein the surface region comprises a curved surface wherein it forms at least a portion of a non-flat flap shape.

19. An ophthalmic device comprising:

a polymerized ophthalmic device encapsulating and shaping hydrogel layer;

a substrate with at least a surface region, wherein a portion of the surface region is planar across its extents and forms a flat flap shape;

electrical contacts formed upon the surface region; and

an electronic element comprising a flexible semiconductor device attached to the electrical contacts, wherein the flexible semiconductor conforms to a non-planar surface.

20. An ophthalmic device of claim 19, further comprising an electroactive optic component.

21. A method of producing an electronic device comprising the steps of:

forming a first substrate with at least one surface region, wherein the surface region is planar across its extents and forms a flat flap shape;

attaching electrical contacts upon the surface region; and

attaching an electronic element comprising a thin flexible semiconductor to the electrical contacts.

22. The method of claim 21, wherein the thin flexible semiconductor comprises a semiconductor layer upon an insulator layer.

23. The electronic device produced by the method of claim 22, wherein the flexible semiconductor comprises a semiconductor layer upon an insulator layer.